Processing of CETRIS® Cement Bonded Particleboards

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Processing finish of CETRIS® Cement Bonded Particleboards

A big advantage of the CETRIS® cement bonded particleboards consists in that they can be processed using standard woodworking machines. For professional processing of CETRIS® boards, only hard metal tools must be used. The CETRIS® boards may be cut, drilled, milled and sanded.

3.1 Cutting

The boards may be cut using special equipment directly at the manufacturing plant according to the customer's requirements. If the customer wants to cut the boards using own equipment, we recommend use of standard hard metal wood-cutting tools (SK laminae). It is also suitable to use special diamond saws to cut the cement bonded particle and cement bonded fibre-glass boards. Due to targeting of an optimal cutting speed of 30 - 60 m/s, it is suitable to use machines with electronic speed regulation. As a rule the boards with surface treatment (CETRIS® FINISH, PROFIL FINISH, LASUR, PROFIL LASUR, DEKOR) must be cut always on the backside (non-treated) side of the board to prevent disruption of the face - finished surface. Immediately after working the boards with surface treatment it is necessary to clean dust from the edge and coat it. When cutting the CETRIS® boards, very fine waste dust is generated. Although the dust does not contain any substances that are harmful to health, we recommend its vacuum-cleaning for reason of environmental protection.

3.2 Drilling

According to the drilling plan submitted by the customer, it is possible to drill the board, including counter-sinking, directly in the manufacturing plant. It is possible to use metal drill-bits (HSS) to drill CETRIS® boards. During manual drilling, it is suitable to use electric drills with electronic speed regulation. As a rule the boards with surface treatment (CETRIS® FINISH, PROFIL FINISH, LASUR, PROFIL LASUR, DEKOR) are drilled from the face (treated) side; drilling from the backside could damage the face - finished surface.



3.3 Milling

CETRIS® cement bonded particleboard can be milled according to customer requirements (e.g. semi-groove, tongue and groove, chamfering of the edges and the like). If the customer wants to machine the board on own equipment, the same principles as apply to the preceding processing methods also apply here. However, when milling, it is necessary to consider the mechanical properties (min. thickness) of the CETRIS® boards.

3.4 Sanding

Full-surface machine sanding of the CETRIS $^{\circ}$ cement bonded particleboards in the manufacturing plant is done on sanded CETRIS $^{\circ}$ PDB floor boards in order to reduce the thickness tolerance to ± 0.3 mm. Manual sanding can be done on the board contact surfaces if it is necessary to eliminate surface unevenness or roughen the board surface. Hand-held electric grinders with 40-80 grain sand paper are used. Also in this case, it is suitable to suck-off the generated dust.



